EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	126	((omura).in. with tetsuji) ((nishikawa).in. with ryuji)	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/25 08:28
L2	1	1 and (thermal processing volatilizing solvent glass paste low melting point frame heat resistant layer)	US-PGPUB; USPAT; USOCR	AND	ON	2009/03/25 08:35
L3	19	thermal process$4 volatil$5 solvent glass paste low melting point (heat near1 resistant near1 layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/03/25 08:37
S1	13861	"445".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 09:25
S2	4769982	@ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 09:26
S3	230706	groove with (substrate plate panel)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 09:27
S4	129955	S2 and S3	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 09:27
S5	13861	"445".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 10:34
S6	4769982	@ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 10:34
S7	230706	groove with (substrate plate panel)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 10:34
S8	340	S5 and S6 and S7	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/08 10:34
S9	2	("7067395" "6825612").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/13 07:18
S10	9	("6974359" "6967438" "6409562" "20020038997" "6195142" "20040051781" "5909081" "6195142" "7067395" "6825612").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/13 07:21
S11	61	(method and substrate and display and groove and seal and glass and paste and heat and laser and "melting point") and @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 07:25
S12	97	(method and substrate and display and groove and seal and glass and paste and heat and "melting point") and @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 07:42

S13	0	substrate and glass and seal and groove and "low melting point" and electroluminescent and (periphery perimeter) and solvent and ("glass paste") and @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 08:54
S14	8	substrate and glass and seal and groove and "low melting point" and display and (periphery perimeter) and solvent and ("glass paste") and @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 08:56
S15	39739	substrate and ((groove trench) with (perimeter periphery edge outside))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 09:06
S16	29818	S15 and @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 09:06
S17	7529	S16 and (display LCD LED OLED OELD FED electroluminescent)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 09:07
S18	200	S17 and (("solder glass") paste) and seal	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 09:08
S19	2	"20070013292".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 09:57
S20	2	"6833668".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:10
S21	2	"20020038997".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:18

S22	2	"6974359".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:20
S23	2	"20020038997".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:23
S24	2	"6409562".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:24
S25	2	"20020180342".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:29
S26	2	"20040188124".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:32
S27	2	"6287669".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:34
S28	72877	(groove trench) with (perimeter periphery edge) with (substrate panel plate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:40
S29	44075	S28 and @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:40
S30	3323	S29 and (display)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:41

S31	7609	S29 and (display "OLED" "OELD" "Fed" "LCD" "LED" electroluminescent)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:42
S32	395	S31 and ((frit glass) with (groove))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:42
S33	21	S32 and ((frit glass) with paste)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 10:43
S34	5	(OLED OELD electroluminescent) and (((groove channel depression ditch notch knotch aperture) near40 (periphery edge perimeter border) near40 (seal$3 bond$3) near40 (frit paste ("low melting")))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 06:35
S35	42552	(OLED OELD electroluminescent)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 06:37
S36	20703	S35 and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 06:37
S37	667571	(groove channel depression ditch notch knotch aperture) near40 (periphery edge perimeter)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 06:38
S38	2524404	(frit paste ("low melting point") bond$3 seal$3)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 06:39
S39	664	S35 and S36 and S37 and S38	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 06:40
S40	524	S39 and @ad<"20030621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 06:41
S41	534139	(groove depression ditch notch knotch aperture) near40 (periphery edge perimeter)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 07:48
S42	287	S35 and S40 and S41	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 07:49
S43	407088	(groove depression ditch notch knotch) near40 (periphery edge perimeter)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 07:54
S44	174	S35 and S40 and S43	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 07:54
S45	1	"20030007117".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 08:56

S46	18341	(groove channel depression notch knotch ditch) near40 (frit solder ("low melting" paste))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 09:02
S47	12897	S46 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 09:03
S48	49	S47 and (OLED OELD electroluminescent)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 09:04
S49	19	S47 and (("glass powder") with (groove trench channel ditch depression notch knotch))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 10:01
S50	218	(("glass powder") with (groove trench channel ditch depression notch knotch))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 10:11
S51	6	S50 and (OLED OELD electroluminescent)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 10:12
S52	113580	(groove channel depression ditch notch knotch) near40 (periphery edge perimeter) near5 (substrate panel plate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 10:25
S53	46316	S52 and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 10:26
S54	65668	S52 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 10:27
S55	183	S54 and (OLED OELD electroluminescent)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 10:27
S56	12	S55 and (frit "glass powder" "solder glass")	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 10:30
S57	12	S55 and (frit "glass powder" "solder glass")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 10:31

S58	12	S55 and (frit "glass powder" "solder glass")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 10:31
S59	3	S55 and ((solvent paste) with (frit "glass powder" "solder glass"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:32
S60	9549	((solvent paste) with (frit "glass powder" "solder glass"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:34
S61	188	(electroluminescent OLED OELD) and((solvent paste) with (frit "glass powder" "solder glass"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:35
S62	78	S61 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:36
S63	4080	((solvent) with (frit "glass powder" "solder glass"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:37
S64	62	S63 and (electroluminescent OLED OELD)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:38
S65	30	S64 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:39
S66	9	S65 and ("low melting point")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:44

S67	25089	((solvent) and (frit "glass powder" "solder glass"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:52
S68	526	S67 and (electroluminescent OLED OELD)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:53
S69	281	S68 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:53
S70	25	S69 and ("low melting point")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 11:54
S71	655	(low with ("heat resistant" "heat resistance")) near40 layer near40 substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:38
S72	46	S71 and (electroluminescent OLED OELD)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:39
S73	35	S72 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:39
S74	2	S71 and ((substrate panel plate) near40(temperature with lower) near40 (frit seal bond))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:48
S75	8	S71 and ((temperature with lower) near40 (frit seal bond))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:50

S76	20	(("low heat resistant")("low heat resistance")) near40 ("color filter")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:56
S77	13	S76 and (("color filter") near40 temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:57
S78	12	S77 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 12:58
S79	11034	temperature near40 (frit "glass powder" "solder glass")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 13:03
S80	2476	temperature near40 (melt$3) near40 (frit "glass powder" "solder glass")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 13:04
S81	1779	S80 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 13:04
S82	34	S81 and (electroluminescent OLED OELD)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 13:05
S83	96424	(OLED OELD electroluminescent)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 13:46
S84	20703	S83 and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 13:46
S85	3085	S84 and "color filter"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 13:47
S86	2264	S85 and @ad<"20030621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 13:47

S87	890	S86 and (("color filter") with substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 13:50
S88	392	(thick$4 near40 "low melting point" near40 glass)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 13:58
S89	571	(thick$4 near40 "low melting point" near40 glass)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 13:58
S90	292	S89 and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 13:59
S91	427	S89 and @ad<"20030621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 13:59
S92	8	thick$4 near40 "low melting point" near40 glass near40 (groove trench channel ditch) near40 substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 14:00
S93	4	S92 and (width with (groove trench channel ditch))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 14:02
S94	34	S89 and (width with (groove trench ditch channel))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 14:28
S95	3	("low melting point glass") near40 substrate near40 remov$3 near40 polish$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 15:04
S96	5	(irregularit$3 near40 (bond seal) near40 substrate) and (thick$4 near40 ("color filter"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 15:16
S97	4962	(irregularit$3 defect$1 bump $1 roughness) near40 (bond seal) near40 substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 15:21

S98	57476	(irregularit$3 defect$1 bump $1 roughness) with (height width depth lenght)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 15:22
S99	712	S97 and S98 and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 15:23
S100	84	S99 and display	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 15:23
S101	84	S99 and display	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 15:23
S102	44249	(irregularit$3 defect$1 roughness) with (height width depth lenght)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 15:27
S103	21868	S102 and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 15:28
S104	5021	S103 and display	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 15:28
S105	0	S104 and ("low melt$3 point glass") near40 (defect$1 irregularities roughness)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 15:30
S106	35	S103 and ("low melting point glass")	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 15:31
S107	5	S106 and "color filter"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 15:33
S108	18797	display and @ad<"20040621" and (width near40 (groove channel ditch notch knotch depression))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 16:49
S109	18352	display and @ad<"20040621" and (width near20 (groove channel ditch notch knotch depression))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 16:50
S110	12	S109 and (thick$4 with (("low melting point") ("solder glass")))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 16:51
S111	203	thickness near40 ("low melting point glass")	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 16:55
S112	158	S111 and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 16:56
S113	115	S112 and display	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 16:56
S114	17	S113 and (groove with (substrate panel plate))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 16:57

S115	51407	(groove with (substrate panel plate) with (periphery perimeter edge))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:03
S116	2713	S115 and display and @ad<"20040621"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:05
S117	63	S116 and (OLED OELD electroluminescent)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:05
S118	0	S117 and "low melting point"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:12
S119	181	S115 and "low melting point"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:13
S120	42	S115 and "low melting point glass"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:13
S121	113580	(groove channel depression ditch notch knotch) near40 (periphery edge perimeter) near5 (substrate panel plate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 17:36
S122	65668	S121 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 17:36
S123	1	S122 and (remove with ("low melting point glass" "solder glass"))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:36
S124	30	paste near40 glass near40 (groove channel notch knotch recess) near40 (remov $3 polish$3 etch$3)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:39
S125	52	paste near40 glass near40 (groove channel notch knotch recess) near40 (remov $3 polish$3 etch$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 17:39
S126	0	S122 and (remov$3 with ("excess glass paste"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 17:57
S127	276	paste near40 glass near40 (groove channel notch knotch recess)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/19 17:58
S128	479	paste near40 glass near40 (groove channel notch knotch recess)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 17:58

S129	270	S128 and (remov$3 polish$3 etch$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 18:00
S130	19	S128 and ((remov$3 polish$3 etch$3) near40 (("low melting") ("solder glass") frit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/19 18:01
S131	4	("glass paste") near40 (groove trench ditch recess channel notch knotch) near40 (remove etch polish grind) near40 glass	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:14
S132	59213	(remove etch polish grind) with (sealant glass frit paste)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:18
S133	6236	S132 and (Solvent with (sealant glass paste frit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:19
S134	4386	S133 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:19
S135	878	S134 and display	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:20
S136	16	S132 and @ad<"20040621" and ((remove etch polish grind) near40 (sealant glass frit paste) near40 (volatil$5 solvent) near40 (groove channel recess slot notch knotch depression ditch))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:27
S137	1	S136 and "glass paste"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:40

S138	600	display and (groove channel recess slot ditch notch knotch depression) and "glass paste"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:48
S139	431	S138 and @ad<"20040621"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:48
S140	0	S139 and (("glass paste") near40 solvent near40 (remove etch polish grind) near40 (groove channel recess slot ditch notch knotch depression))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:50
S141	3	S139 and (("glass paste") near40 solvent near40 (remove etch polish grind))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:50
S142	62	S139 and (("glass paste") near40 (groove channel recess slot ditch notch knotch depression))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 06:52
S143	9	S142 and ((flatten remove polish etch grind) near40 (glass frit ("glass paste")) near40 (groove channel recess notch knotch depression slot ditch))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 07:25
S144	2	S139 and (remov$3 with ("low melting point glass"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 07:40
S145	2	S139 and ((remov$3 polish grind etch) with ("low melting point glass"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 07:41
S146	51	S139 and ((remov$3 polish grind etch) with ("glass paste"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 07:42

S147	21	S146 and (("glass paste") with (groove channel recess knotch notch ditch))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 07:46
S148	3553	(flatten polish smooth) near40 (seal$3 frit "glass paste" glass) near40 (groove channel recess)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 07:51
S149	169	S148 and @ad<"20040621" and display	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 07:52
S150	0	S149 and shimizu.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 08:11
S151	5	S148 and shimizu.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 08:12
S152	0	S147 and shimizu.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 08:12
S153	0	S146 and shimizu.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 08:13
S154	195	S132 and shimizu.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 08:13
S155	1	shimizu.in. and @ad<"20040621" and "glass paste" and frame and "resin dispersion medium"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/20 08:15

S156	10	("5867149" "20050042364" "20030141804" "20020030437" "5392144" "5997377" "20050029513" "20060029513" "20060202013" "20040160184").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/20 08:27
S157	10	("5867149" "20050042364" "20030141804" "20020030437" "5392144" "5997377" "20050029513" "20060029513" "20060202063" "20040160184").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/20 08:29
S158	9	("5867149" "20050042364" "20030141804" "20020030437" "5392144" "5997377" "20050029513" "20050029513" "20060202063" "20040160184").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/20 08:30
S159	9	("5867149" "20050042364" "20030141804" "20020030437" "5392144" "5997377" "20050029513" "20060202613" "20040160184").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/20 08:32
S160	3	(solvent near40 (groove trench recess ditch channel) near40 (heat thermal volatiz$3) near40 paste near40 glass)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/28 08:47
S161	4	(solvent near40 (groove trench recess ditch channel) near40 (heat thermal volatiz$3) near40 paste near40 glass)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/28 08:48
S162	2	"5392144".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/28 09:05
S163	0	("solder glass") near40 powder near40 solvent near40 heat$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:04
S164	25	("glass paste") near40 powder near40 solvent near40 heat$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:04

S165	9	S164 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 14:05
S166	0	("solder glass") with seal with display with @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 14:10
S167	0	("solder glass") with seal with display with @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:10
S168	8	("solder glass") near40 powder near40 solvent	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:12
S169	8	S168 and heat	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:12
S170	13911	"445".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 14:13
S171	0	S170 and S169	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:13
S172	2	"5392144".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:38
S173	336	("color filter") near40 (panel plate substrate) near40 (("heat resistance") ("heat resistant"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:40
S174	94	S173 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 14:41
S175	91	S174 and display	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 14:41
S176	10	("color filter") near40 (panel plate substrate) near40 ((" low heat resistance") ("low heat resistant"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:45

S177	6	S176 and (("low heat resistance") near20 temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/30 14:51
S178	2	"2004199894"	EPO; JPO; DERWENT	OR	ON	2008/05/30 15:09
S179	1	"5867149".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:14
S180	1	("color fiter") with (panel plate substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:18
S181	1	("color fiter") near40 (panel plate substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:20
S182	1	("color fiter") near40 (panel plate substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:21
S183	27928	("color filter") near40 (panel plate substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:22
S184	16061	S183 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:22
S185	14832	S184 and display	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:22
S186	638	S185 and (("color filter") near40 (temperature))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:23
S187	3	S186 and oled	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:23
S188	596	S185 and (("color filter") near20(temperature))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:30
S189	596	S185 and (("color filter") near20 (temperature))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:30
S190	468	S185 and (("color filter") near10 (temperature))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:31
S191	10	S186 and (("melting point") with glass)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:43
S192	0	S186 and (("melting point") with ("solder glass"))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:47
S193	200	(("melting point") with ("solder glass"))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:47
S194	145	S193 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:47
S195	39	S194 and display	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:48
S196	42	(("melting point") with ("solder glass")) with temperature	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:52
S197	32	S196 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:52
S198	3554	Hsiao.in.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 15:59

S199	33	S198 and "color filter" and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 16:00
S200	2	S199 and temperature and withstand	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 16:00
S201	1	"20060202613".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 16:53
S202	10	takaoka.in. and ("low melting point")	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 16:56
S203	10	S202 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 16:57
S204	0	takaoka.in. and ("IC packaging")	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 17:00
S205	0	takaoka.in. and ("glass powder").ab.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 17:01
S206	1	"20040241920".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/30 17:13
S207	2	"01234339".pn.	EPO; JPO; DERWENT	OR	ON	2008/05/30 17:14
S208	13929	"445".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:53
S209	4775727	@ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:53
S210	231732	groove with (substrate plate panel)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:53
S211	341	S208 and S209 and S210	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:53
S212	124	S211 and paste	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:53
S213	12	S212 and (remove with paste)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:53
S214	27	S210 and (remove near40 paste near40 (groove channel ditch recess))	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 15:09
S215	556	(remove grind polish sandblast cut) near40 paste near40 (groove channel recess slot ditch notch knotch depression)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 15:34
S216	366	S215 and @ad<"20040611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 15:34
S217	18	S216 and ("low melting")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/10 15:35

S218	1	"6195142".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 05:57
S219	1	"20040051781".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 05:59
S220	3	"2001189191"	EPO; JPO; DERWENT	OR	ON	2008/06/11 06:03
S221	13929	"445".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 09:52
S222	4775727	@ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 09:52
S223	231732	groove with (substrate plate panel)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 09:52
S224	341	S221 and S222 and S223	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 09:52
S225	22	S224 and "low melting point glass"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 09:52
S226	35166	(313/498-512 315/169.1,169.3 428/690-691,917 438/26-29,34,82 257/40,72,98-100,642-643,759 427/66,532-535,539).ccls. (445/24-25 427/58,64,66).ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 10:10
S227	21995	S226 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 10:10
S228	6572	S227 and (OLED OELD electroluminescent)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 10:10
S229	17	S228 and "low melting point glass"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 10:11
S230	1	"2001189191".pn.	US-PGPUB; USPAT; USOCR; JPO	OR	ON	2008/06/11 13:05
S231	1	"20030168972".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/16 11:38
S232	1	"20040241920".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/16 12:25
S233	1	"5867149".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/16 12:34
S234	581	(color near1 filter) with (seal $3 near1 substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/16 12:35
S235	1	S231 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/16 12:35
S236	204	S234 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/16 12:36
S237	92	S236 and (PDP plasma)	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/16 12:36

S238	111	(glass near1 paste) with groove	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 06:50
S239	47	S238 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/29 06:50
S240	7053055	(groove in (substrate panel plate))	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/29 07:21
S241	0	display and @ad<"20040611" and (groove near1 in near1 (substrate plate panel))	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/29 07:26
S243	13826	display and (groove near3 (substrate panel plate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 07:27
S244	7330	S243 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/29 07:27
S245	1330	S244 and (("445" "437" "438" "427" "428" "257" "252" "313").clas.)	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/29 07:28
S246	60	S245 and (glass near1 paste)	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/29 07:29
S247	1	("5867149").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/29 08:17
S248	238328	groove with (substrate plate panel)	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/30 15:16
S249	1295	S248 and (laser with filter)	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/30 15:16
S250	413	S249 and display	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/30 15:17
S251	285	S250 and @ad<"20040611"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/30 15:17
S252	1	"5867149".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/31 06:43
S253	118	(color near1 filter) and ((solder near1 glass) ("low melting point glass")) and @ad<"20040611" and display	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 07:06
S254	211	(color near1 filter) and ((solder near1 glass) ("low melting point glass")) and display	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 07:46

S255	93	S254 not S253	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 07:46
S256	307	((omura).in. with tetsuji) ((nishikawa).in. with ryuji)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 08:33
S257	1	S256 and (frame groove substrate sealing glass paste low melting point powder solvent thermal heat resistant laser).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/31 08:35
S258	1	(frame groove substrate sealing glass paste low melting point powder solvent thermal heat resistant laser).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/31 08:35

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